

35. A method for generating a polishing pad structure for utilization in chemical mechanical polishing, comprising:

- providing a reinforcement layer;
- applying a first adhesive film on the reinforcement layer;
- attaching a cushioning layer on the first adhesive film;
- applying a second adhesive film on the cushioning layer;

attaching a seamless polymeric polishing pad on the second adhesive layer, the polymeric polishing pad having a grooved top surface, the seamless polishing pad being generated by pouring a polymeric gel into a mold; and

curing the polishing pad structure for about 20 hours in a temperature of about 200 F.

REMARKS

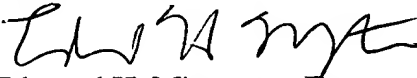
Claims 6, 13, 18-20, 26-27, and 29 have been amended to better define that which the Applicants consider to be the invention. Claims 1-35 are pending.

Claims 6, 13, 18-20, 26-27, and 29 were amended to incorporate the feature of the reinforcement layer being made from one of stainless steel and a Kevlar-type material as is supported on page 20, lines 9 through 13, and page 25 lines 12 through 20 of the original specification as filed. Therefore, the amendments do not add new matter. In addition, as discussed in the Amendment of November 19, 2002, the Office Action dated August 19, 2002 should not have been a final rejection. Therefore, Applicants request that the finality of the Office Action dated August 19, 2002 be withdrawn and further submit that the amendments should be entered.

Applicants respectfully submit that the pending claims are in condition for allowance. Accordingly, a notice of allowance is respectfully requested. If the Examiner has any

questions concerning this paper, the Examiner is kindly requested to contact the undersigned at (408) 749-6900. If any additional fees are due in connection with the filing this paper, the Commissioner is also authorized to charge Deposit Account No. 50-0805 (Order No. LAM2P223A).

Respectfully submitted,
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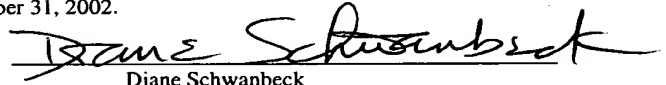
Response Under 37 C.F.R. § 1.116
Expedited Procedure
Examining Group 3723
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of)	
)	Examiner: Nguyen, Dung V.
Cangshan XU et al.)	
)	Art Unit: 3723
Application No. 09/752,509)	
)	Docket No. LAM2P223A
Filed: December 27, 2000)	
)	Date: December 31, 2002
For: METHODS FOR MAKING)	
REINFORCED WAFER POLISHING)	
PADS AND APPARATUSES)	
IMPLEMENTING THE SAME)	

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231 on December 31, 2002.

Signed: 
Diane Schwanbeck

MARKED-UP CLAIMS

6. (Amended) A seamless polishing apparatus for utilization in chemical mechanical polishing as recited in claim 1, wherein the reinforcement layer is one of [a] stainless steel [layer] and a Kevlar-type material.

13. (Amended) A seamless polishing apparatus for utilization in chemical mechanical polishing, comprising:

a polishing pad, the polishing pad being shaped like a belt and configured to have no seams; and

a base belt, the base belt including a reinforcement layer and a cushioning layer, the reinforcement layer being one of [a] stainless steel [layer] and a Kevlar-type material;

wherein the cushioning layer is an intermediary layer between the continuous pad and the reinforcement layer.

18. (Amended) A polishing structure for utilization in chemical mechanical polishing, comprising:

a polishing pad, the polishing pad being shaped like a belt and configured to be a contiguous unit, the polishing pad being made of a polymeric material; and

a base belt, the base belt including a reinforcement layer and a cushioning layer, the reinforcement layer being one of [a] stainless steel [layer] and a Kevlar-type material;

wherein the cushioning layer is an intermediary layer between the polishing pad and the reinforcement layer, the cushioning layer being a polymeric material.

19. (Amended) A polishing structure for utilization in chemical mechanical polishing as recited in claim 18, wherein the [steel layer] reinforcement layer and the cushioning layer are attached by a first adhesive film, and the cushioning layer and the polishing pad are attached by a second adhesive film.

20. (Amended) A seamless polishing apparatus for utilization in chemical mechanical polishing, comprising:

a polishing pad, the polishing pad being shaped like a belt and configured to be a contiguous unit and to have grooves on a pad surface, the polishing pad being made up of polyurethane; and

a base belt, the base belt including a reinforcement layer and a cushioning layer, the reinforcement layer being one of [a] stainless steel [layer] and a Kevlar-type material, the reinforcement layer and the cushioning layer being attached by way of a first adhesive film, the base belt and the polishing pad being attached by way of a second adhesive film;

wherein the cushioning layer is an intermediary between the polishing pad and the reinforcement layer, the cushioning layer being a polyurethane material.

26. (Amended) A seamless polishing apparatus for utilization in chemical mechanical polishing as recited in claim 24, wherein the reinforcement layer is one of [a] stainless steel [layer] and a Kevlar-type material.

27. (Amended) A seamless polishing apparatus for utilization in chemical mechanical polishing, comprising:

a polishing pad, the polishing pad being shaped like a belt and configured to have no seams, and the polishing pad being made of a polymeric material, and the polishing pad being between about 30 mils and about 100 mils in thickness and configured to have a grooved top surface; and

a base belt, the base belt including a reinforcement layer and a cushioning layer, the reinforcement layer being one of [a] stainless steel [layer] and a Kevlar-type material, and the cushioning layer being between about 10 mils and about 100 mils in thickness, and the reinforcement layer being between about 5 mils and 50 mils in thickness;

wherein the cushioning layer is an intermediary layer between the polishing belt pad and the base belt.

29. (Amended) A method for generating a polishing pad structure for utilization in chemical mechanical polishing as recited in claim 28 wherein the reinforcement layer is one of [a] stainless steel [layer] and a Kevlar-type material.